



Session Title:	[WC2] Advanced Cleaning Technology
Session Date:	November 22 (Wed.), 2023
Session Time:	10:20-11:30
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Jinsub Park (Hanyang Univ., Korea)

[WC2-1] [Invited]

10:20-10:50

New Cleaning and Etch Solution Approaches for Advanced sub 5nm Technology Nodes

Andreas Klipp, Haci Osman Guevenc, and Francisco Javier Lopez Villanueva (BASF SE, Germany)

[WC2-2] [Invited]

10:50-11:10

BOE-Based High Selective SiO₂ Etching Technology Applicable to Next-Generation Semiconductor Manufacturing Process

Myung Ho Lee, Bun Sung Jung, Hak Soo Kim, and Myung Geun Song (ENF Tech. Co., Ltd., Korea)

[WC2-3]

11:10-11:30

Fenton Reaction for Enhancing Ag-Film Polishing-Rate in Chemical-Mechanical-Planarization

Man-Hyup Han (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), and Jae-Gun Park (Hanyang Univ., Korea)